

FIG. 1

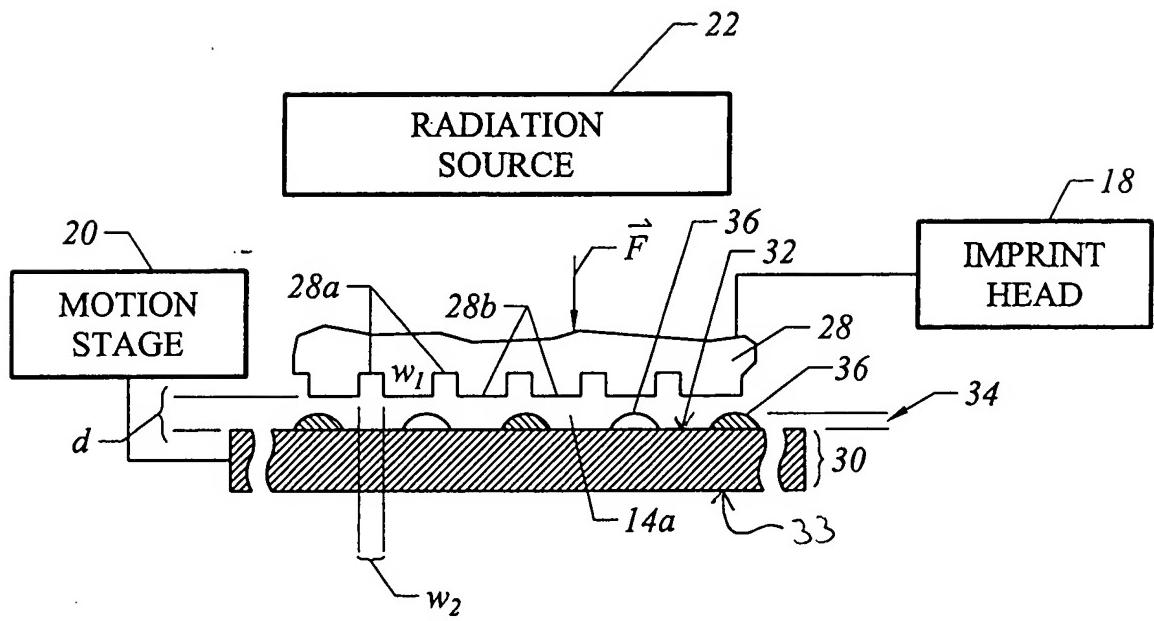


FIG. 2

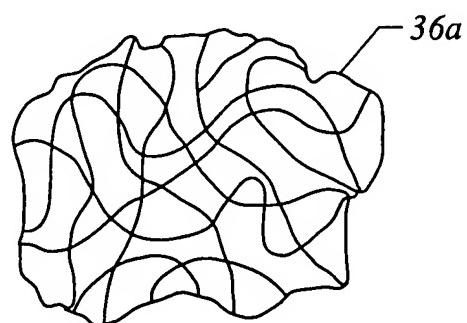


FIG. 3

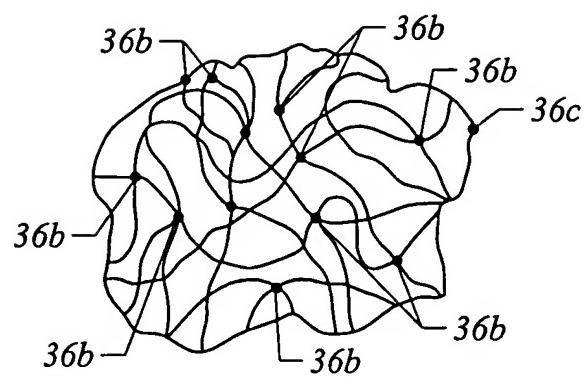


FIG. 4

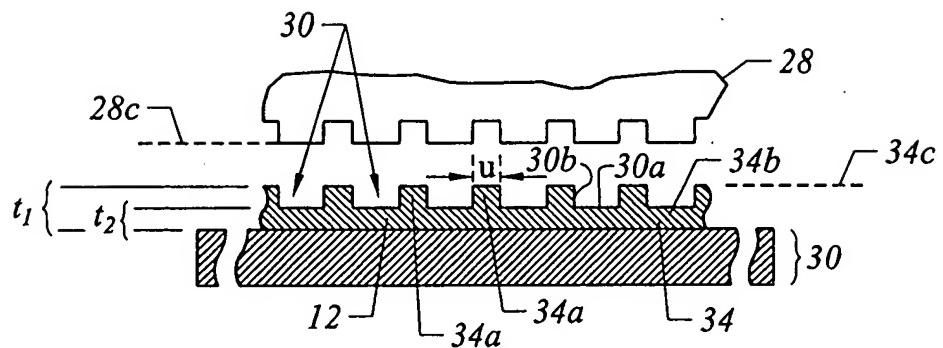


FIG. 5

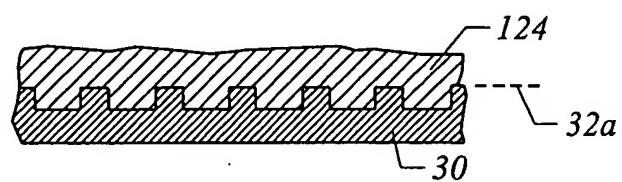


FIG. 6

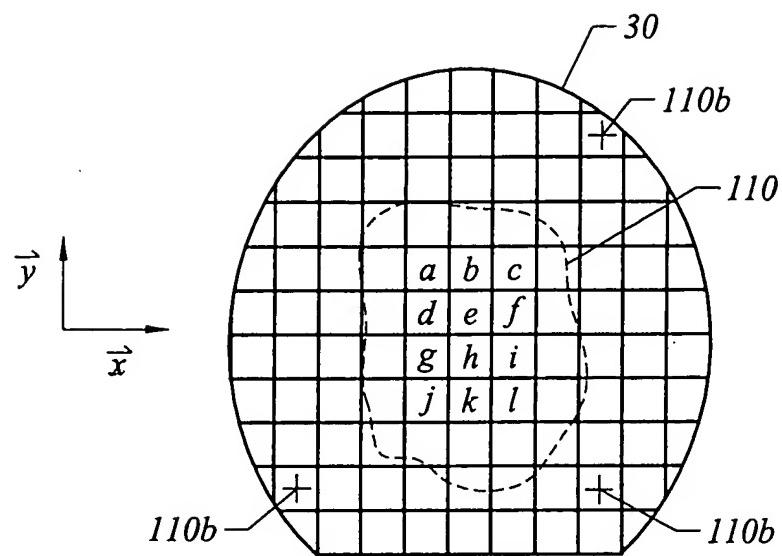


FIG. 7

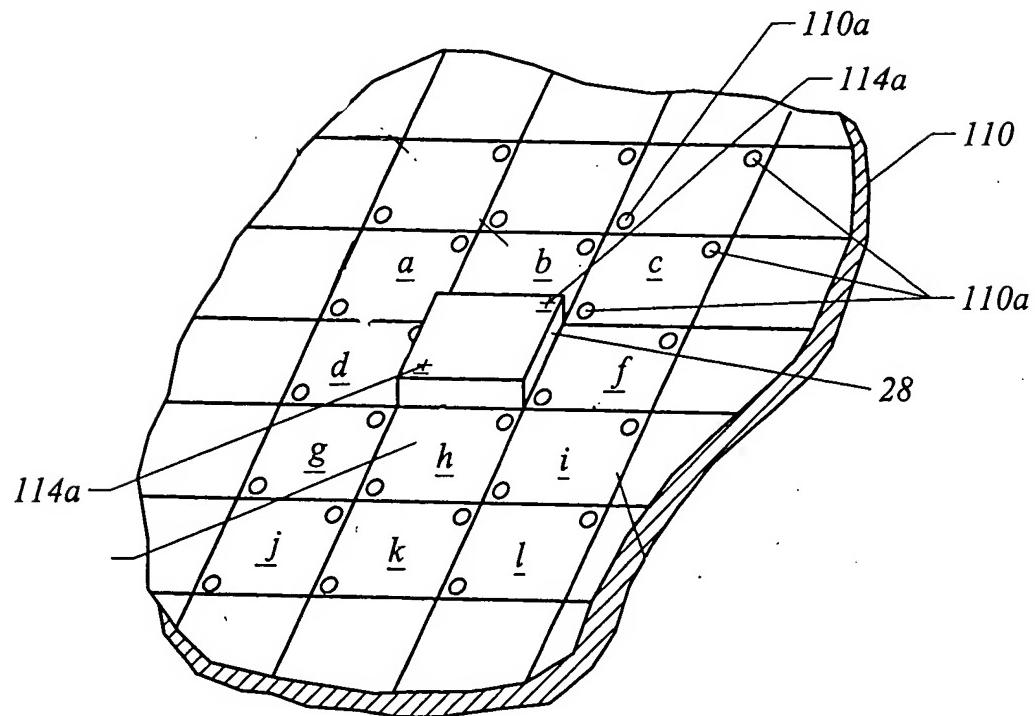


FIG. 8

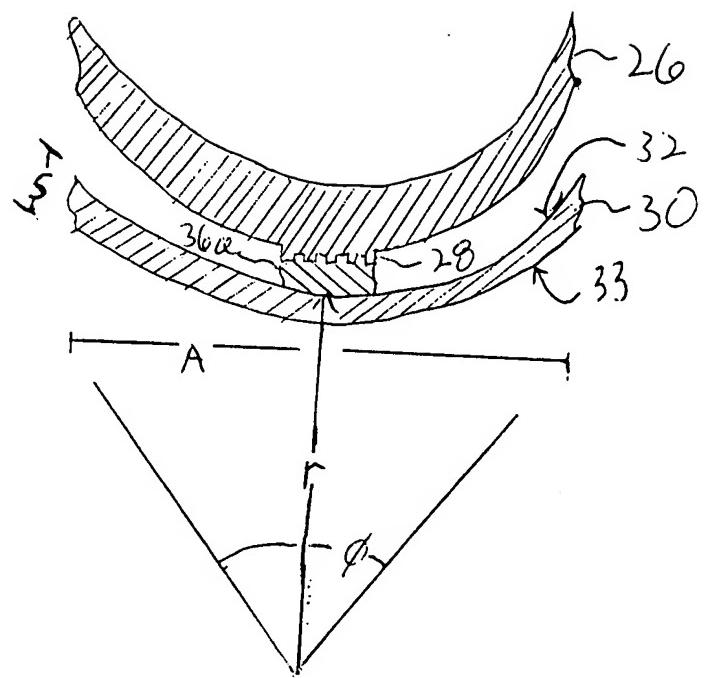


Fig. 9

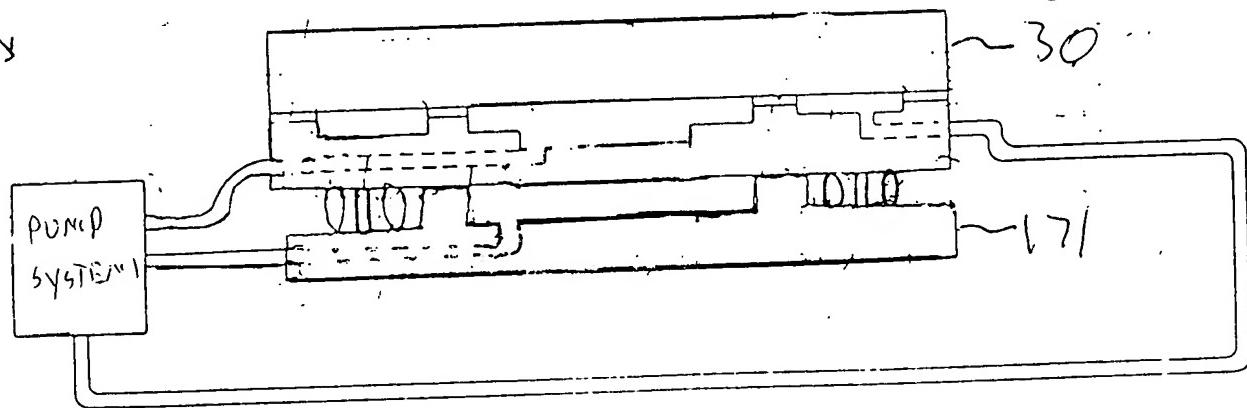
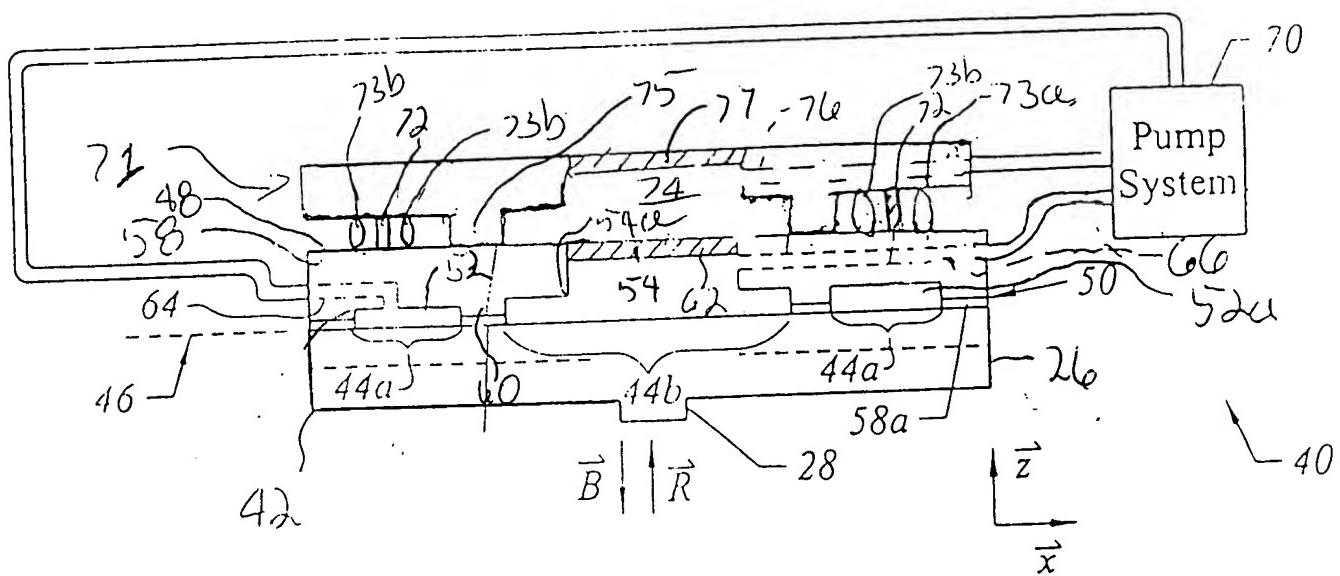


Fig. 10

DEFINE A REGION ON THE WAFER IN WHICH TO PRODUCE A RECORDED PATTERN BY DEPOSITING LIQUID MATERIAL

L100

PRODUCE A CONTOURED SURFACE IN THE REGION BY BENDING THE WAFER OUT OF THE NEUTRAL STATE

L102

CONTACT THE REGION ON THE WAFER WITH THE TEMPLATE BY HAVING A MOLD ON THE TEMPLATE CONTACT THE LIQUID MATERIAL

L104

CREATE DIMENSIONAL VARIATIONS IN THE ORIGINAL PATTERN ON THE MOLD BY BENDING THE TEMPLATE OUT OF THE NEUTRAL STATE

L106

SOLIDIFY THE LIQUID MATERIAL TO RECORD A PATTERN MADE THEREIN BY THE MOLD

L108

SEPARATE THE MOLD FROM THE SOLIDIFIED LIQUID MATERIAL AND RETURN THE WAFER TO THE NEUTRAL STATE

L110

FIG. 11

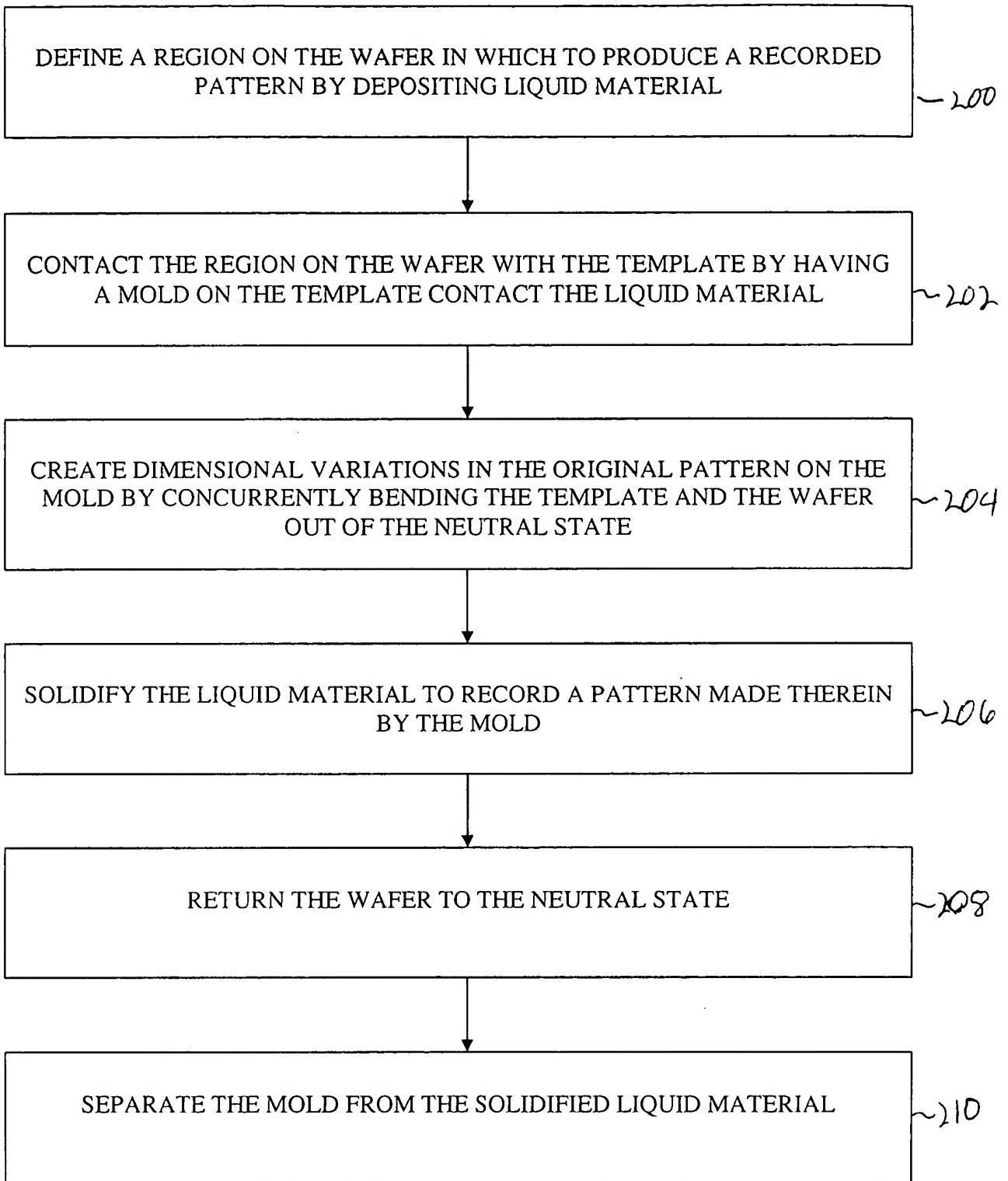


FIG. 12